## 503523117 10/14/2015

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
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### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14882347

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	CLAIRE LEMIEUX
SIGNATURE: /Claire Lemieux/	
DATE SIGNED:	10/14/2015

#### **Total Attachments: 2**

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PATENT 503523117 REEL: 036793 FRAME: 0535

#### **ASSIGNMENT**

WHEREAS, I/we, Masato OKABE of c/o Yamato Mishin Seizo Kabushiki Kaisha, Toyonaka Plant, 10-3, Minami-machi 2-chome, Hotarugaike, Toyonaka-shi, Osaka 560-0034 Japan ("Assignor"), am/are the inventor(s) of an invention entitled "SEWING MACHINE" that is the subject matter of: (check all that apply)

[x]	an application for Letters Patent which claims the priority of Japanese Patent Application No. 2014-212891 filed on October 17, 2014.
[ ]	an application made under the Patent Cooperation Treaty which is identifiable at WIPO by Application No. PCT/filed on,
[ ]	an application for Letters Patent which is identifiable in the Patent Office of by Application No filed on:
the la	REAS, <u>Yamato Mishin Seizo Kabushiki Kaisha</u> , a <u>corporation</u> organized and existing under ws of <u>Japan</u> ("Assignee"), and having offices at 4-12, Nishi-tenma 4-chome, Kita-ku, a-shi, Osaka 530-0047 Japan is desirous of acquiring the entire right, title and interest in and to vention, the applications, and any and all Letters Patent or similar foreign or domestic legal ction
[ x ] [ ]	in the United States in all other countries or jurisdictions;
	(m) mm m a m m a la l

"NOW THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged,

- a) I/we agree to transfer, and
- b) I/we do hereby transfer,

to Assignee, its successors and assigns, effective as of October 17, 2014 nunc pro tunc, my/our entire right, title and interest in the above named countries and jurisdictions in and to the following including the right to sue for past infringement: the invention, the above-identified applications, all applications from which any of the above-identified applications claim priority, corresponding U.S. and non-U.S. applications, any continuation, division, renewal, or substitute for the applications, all Letters Patent, any reissue, re-examination, or similar legal protection issuing related to the Letters Patent, and all rights and benefits under any applicable treaty or convention, and I/we authorize the Director of the United States Patent and Trademark Office or foreign equivalent to issue the Letters Patent or similar legal protection to the Assignee."

I/We authorize the Assignee, its successors and assigns, to insert in this instrument the filing date(s) and application numbers when ascertained. I/We further authorize the Assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent or similar legal protection, in its own name if desired, in the above named countries and jurisdictions and appoint Assignee the common representative in the above identified international application and any international application for the invention.

I/We represent to the Assignee, its successors and assigns, that I/we shall not execute any writing or do any act whatsoever conflicting with this Assignment. I/We, my/our executors or administrators, will at any time upon request, without additional consideration, but at the expense of the Assignee, its successors and assigns, execute and deliver to Assignee or its legal representatives such additional writings and do such additional acts as the Assignee, its successors and assigns, may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the

Letters Patent or similar legal protection on the invention in any and all countries and jurisdictions, including without limitation providing testimony in any related interference, litigation or proceeding. To the extent that I/we, my/our executors or administrators are unable or unavailable to execute and deliver to Assignee or its legal representatives such additional writings and do such additional acts as Assignee, its successors and assigns may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries and jurisdictions, I/we, my/our executors or administrators hereby authorize Assignee, its successors and assigns to act on my/our behalf/behalves.

If any provision(s) of this Assignment are held unenforceable or in conflict with the law of any jurisdiction, the validity of the remaining provisions will not be affected by such holding and the part held unenforceable in or in conflict with the law of one jurisdiction will remain in effect for other jurisdictions until held unenforceable or in conflict with the law of that jurisdiction.

masato	Okabe
Masato OKABE	
(Inventor / Assign	nor)
August 31, 2	015

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**RECORDED: 10/14/2015**